



Form PTO-1595 TRADEN HEET U.S. DEPARTMENT OF COMMERCE (Rev. 03/01) U.S. Patent and Trademark Office OMB No. 0651-0027 (exp. 5/31/200\_ 102263716 To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof. 2. Name and address of receiving party(ies) 1. Name of conveying party(ies): 10-23-02 Name: Sony Corporation Kiyohisa Tanaka Internal Address: Additional name(s) of conveying party(ies) attached? 📮 Yes 🔼 No 3. Nature of conveyance: Assignment Merger | Street Address: 7-35 Kitashinagawa Security Agreement ☐ Change of Name 6-Chome, Shinagawa-ku, Tokyo, Japan Other City:\_\_\_\_\_Zip:\_\_\_\_ Execution Date: October 1, 2002 4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: A. Patent Application No.(s) B. Patent No.(s) 10/216,262 Additional numbers attached? 📮 Yes 🔼 No 5. Name and address of party to whom correspondence 6. Total number of applications and patents involved: concerning document should be mailed: Name: Robert J. Depke 7. Total fee (37 CFR 3.41).....\$\_\_\_ Enclosed Internal Address: Holland & Knight LLC Authorized to be charged to deposit account 8. Deposit account number: Street Address: 55 West Monroe Street Suite 800 (Attach duplicate copy of this page if paying by deposit account) City: Chicago State: IL Zip: 60603 DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Robert J. Depke

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents & Trademarks, Box Assignments

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**PATENT** REEL: 013416 FRAME: 0750

902/09840/00

Docket Number:	075834 00144
DOCKEL NUMBER.	<u>U/JUJ4.UU174</u>

## ASSIGNMENT

	WHEREAS, I,	as a below named	l inventor, residi	ing at the address	stated next to	my name, am a	sole inventor (i	if
only one name is	listed below) or	a joint inventor	(if plural names :	are listed below) o	of certain new a	and useful impro	ovements in	

## SOLID-STATE IMAGE PICKUP DEVICE

for which an application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, the entire right, title and interest in the said invention, said application, including any divisions and continuations as well as any reissues and reexaminations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

•	rney(s) of record in this application to insert the serial number and No. 10/216,262 Filing Date: August 9, 2002
This assignment executed on the dates indica	ted below.
Kiyohisa Tanaka	
Name of first or sole inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of first or sole inventor	
Rigishisa Timaka Signature of First or sole inventor	October 1, 2002
Signature of First or sole inventor	Date of this Assignment

PATENT REEL: 013416 FRAME: 0751

**RECORDED: 10/23/2002**